

FRONTGRADE DATASHEET UT54ACTS240E

Octal Buffers & Line Drivers Inverted Three State Outputs

1/1/2019

Version #:1.0.0



Features

- Three-state outputs drive bus lines or buffer memory address registers
- 0.6μm CRH CMOS process
 - Latchup immune
- · High speed
- · Low power consumption
- Wide power supply operating range of 3.0V to 5.5V
- Available QML Q or V processes
- · 20-lead flatpack
- UT54ACTS240E-SMD-5962-96569

Description

The UT54ACTS240E is an inverting octal buffer and line driver which improves the performance and density of three-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device is characterized over full military temperature range of -55°C to +125°C.

Function Table

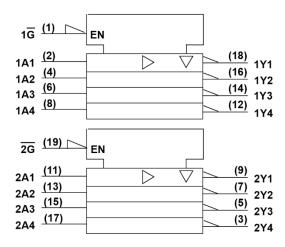
INPUTS		OUTPUT
<u>1G, 2G</u>	А	Υ
L	L	н
L	н	L
н	X	z

Pinouts 20-Lead Flatpack Top View

1G □	1	20	V _{DD}
1A1	2	19	<u>2G</u>
2A4	3	18	1Y1
1A2	4	17	2A4
2Y3	5	16	1Y2
1A3	6	15	2A3
2Y2	7	14	1Y3
1A4	8	13	2A2
2Y1	9	12	1Y4
v _{ss} ———	10	11	2A1



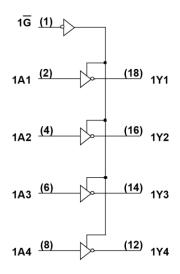
Logic Symbol

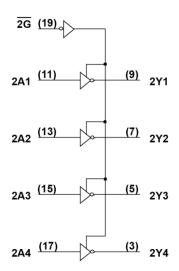


Note:

1. Logic symbol in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Logic Diagram







Operational Environment¹

Parameter	Limit	Units
Total Dose	1.0E6	rads(Si)
SEU Threshold ²	108	MeV-cm²/mg
SEL Threshold	120	MeV-cm²/mg
Neutron Fluence	1.0E14	n/cm²

Notes:

- 1. Logic will not latchup during radiation exposure within the limits defined in the table.
- 2. Device storage elements are immune to SEU affects.

Absolute Maximum Ratings

Symbol	Parameter	Limit	Units
V_{DD}	Supply voltage	-0.3 to 7.0	V
V _{I/O}	Voltage any pin	3 to V _{DD} +.3	V
T _{STG}	Storage temperature range	-65 to +150	°C
T _J	Maximum junction temperature	+175	°C
T _{LS}	Lead temperature (soldering 5 seconds)	+300	°C
Θ _{JC}	Thermal resistance junction to case	15.0	°C/W
l ₁	DC input current	±10	mA
P_D^2	Maximum package power dissipation permitted @ $T_C = +125^{\circ}C$	3.3	W

Note:

- Stresses outside the listed absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, functional operation of the device at these or any other conditions beyond limits indicated in the operational sections is not recommended. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- 2. Per MIL-STD-883, method 1012.1, section 3.4.1, P_D =(Td(max) T_C (max)) / Θ_{JC}



Recommended Operating Conditions

Symbol	Parameter	Limit	Units
V_{DD}	Supply voltage	3.0 to 5.5	V
V _{IN}	Input voltage any pin	0 to V _{DD}	V
T _C	Temperature range	-55 to +125	°C

DC Electrical Characteristics for the UT54ACTS240E⁷

 $(V_{DD} = 3.0V \text{ to } 5.5V; V_{SS} = 0V,^6 - 55^{\circ}C < T_C < +125^{\circ}C)$

Symbol	Description	Condition	MIN	MAX	Units
V _{IL1}	Low-level input voltage ¹	V _{DD} from 4.5V to 5.5V		0.8	V
V _{IL2}	Low-level input voltage ¹	V _{DD} from 3.0V to 3.6V		0.8	V
V _{IH1}	High-level input voltage ¹	V _{DD} from 4.5V to 5.5V	0.5 V _{DD}		V
V _{IH2}	High-level input voltage ¹	V _{DD} from 3.0V to 3.6V	2.0		V
lin	Input leakage current	$V_{IN} = V_{DD}$ or V_{SS}	-1	1	μΑ
V _{OL1}	Low-level output voltage ³	I _{OL} = 12mA V _{DD} = 4.5V to 5.5V		0.4	V
V _{OL2}	Low-level output voltage ³	IOL = 8mA V _{DD} = 3.0V to 3.6V		0.4	V
V _{OH1}	High-level output voltage ³	I _{OH} = -12mA V _{DD} from 4.5V to 5.5V	0.7 V _{DD}		V
V _{OH2}	High-level output voltage ³	IOH = -8mA V _{DD} from 3.0V to 3.6V	2.4		V
OS1	Short-circuit output current ^{2, 4}	$V_O = V_{DD}$ and V_{SS} V_{DD} from 4.5V to 5.5V	-300	300	mA
l _{OS2}	Short-circuit output current ² , ⁴	$V_O = V_{DD}$ and V_{SS} V_{DD} from 3.0V to 3.6V	-200	200	mA
I _{OL1}	Low level output current ⁹	$V_{IN} = V_{DD}$ or V_{SS} $V_{OL} = 0.4V$ V_{DD} from 4.5V to 5.5V	12		mA
I _{OL2}	Low level output current ⁹	$V_{IN} = V_{DD}$ or V_{SS} $V_{OL} = 0.4V$ V_{DD} from 3.0V to 3.6V	8		mA
Ј он1	High level output current ⁹	$V_{IN} = V_{DD} \text{ or } V_{SS}$ $V_{OH} = V_{DD} - 0.4V$ $V_{DD} \text{ from } 4.5V \text{ to } 5.5V$	-12		mA



Symbol	Des	cription	Condition	MIN	MAX	Units
I _{OH2}	High level output cu	urrent ⁹	$V_{IN} = V_{DD}$ or V_{SS} $V_{OH} = V_{DD}$ -0.4V V_{DD} from 3.0V to 3.6V	-8		mA
I _{OZH}	Three-state output leakage current, high		$G = 5.5V$; for all other inputs $V_{IN} = V_{DD}$ or V_{SS} ; $V_{OUT} = V_{DD}$ $V_{DD} = 5.5V$		30	μА
l _{ozl}	Three-state output	leakage current, low	G = 5.5V; for all other inputs $V_{IN} = V_{DD}$ or V_{SS} ; $V_{OUT} = V_{SS}$ $V_{DD} = 5.5V$		-30	μΑ
P _{total1}	Power dissipation ² ,	8	C _L = 50pF V _{DD} = 4.5V to 5.5V		1.5	mW/ MHZ
P _{total2}	Power dissipation ² ,	8	C _L = 50pF V _{DD} = 3.0V to 3.6V		0.75	mW/ MHZ
		Pre-Rad All Device Types			10	
I _{DDQ}	Quiescent Supply Current	Post-Rad Device Type - 03	$V_{IN} = V_{DD} \text{ or } V_{SS}$ $V_{DD} = V_{DD} \text{ MAX}$		50	μΑ
	Post-Rad Device Type - 02				130	
ΔI _{DDQ}	Quiescent Supply Co	urrent Delta	For input under test $V_{IN} = V_{DD} - 2.1V$ For all other inputs $V_{IN} = V_{DD}$ or V_{SS} $V_{DD} = 5.5V$		1.6	mA
C _{IN}	Input capacitance 5		ʃ = 1MHz, V _{DD} = 0V		15	pF
Соит	Output capacitance	5	∫ = 1MHz, V _{DD} = 0V		15	pF

Notes:

- 1. Functional tests are conducted in accordance with MIL-STD-883 with the following input test conditions: $V_{IH} = V_{IH}$ (min) + 20%, 0%; $V_{IL} = V_{IL}$ (max) + 0%, 50%, as specified herein, for TTL, CMOS, or Schmitt compatible inputs. Devices may be tested using any input voltage within the above specified range, but are guaranteed to V_{IH} (min) and V_{IL} (max).
- 2. Supplied as a design limit but not guaranteed or tested.
- 3. Per MIL-PRF-38535, for current density ≤ 5.0E5 amps/cm², the maximum product of load capacitance (per output buffer) times frequency should not exceed 3,765 pF/MHz.
- 4. Not more than one output may be shorted at a time for maximum duration of one second.
- 5. Capacitance measured for initial qualification and when design changes may affect the value. Capacitance is measured between the designated terminal and V_{SS} at frequency of 1MHz and a signal amplitude of 50mV rms maximum.
- 6. Maximum allowable relative shift equals 50mV.
- 7. Device type 02 is only offered with a TID tolerance guarantee of 3E5 rads(Si) or 1E6 rads(Si) and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A and section 3.11.2. Device type 03 is only offered with a TID tolerance guarantee of 1E5 rads, 3E5 rads(Si), and 5E5 rads(Si), and is tested in accordance with MILSTD-883 Test Method 1019 Condition A.
- 8. Power does not include power contribution of any TTL output sink current.
- 9. Guaranteed by characterization, but not tested.



AC Electrical Characteristics for UT54ACTS240E²

 $(V_{DD} = 3.0V \text{ to } 5.5V; V_{SS} = 0V^{-1}, -55^{\circ}C < T_{C} < +125^{\circ}C)$

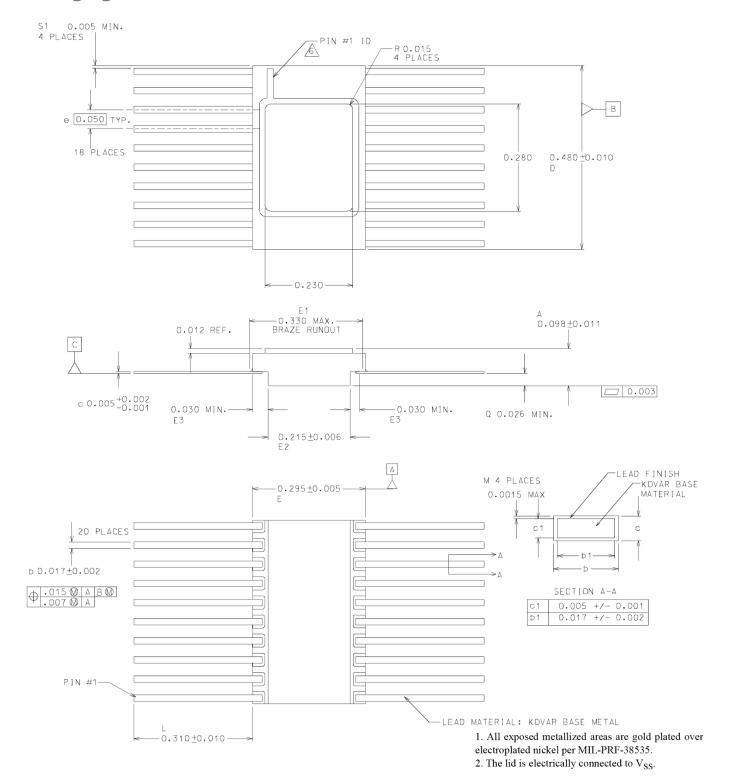
Symbol	Parameter	Condition	VDD	MIN	MAX	Unit	
		C _L = 50pF	3.0V to 3.6V	1	12	200	
t _{PHL}	Input to Yn	C _L = 50pr	4.5V to 5.5V	1	11	ns	
	Input to Yn	C _L = 50pF	3.0V to 3.6V	1	12	ns	
t _{PLH}	input to 111	C _L = 50pr	4.5V to 5.5V	1	9	ns	
	- Clause Valletine	C - F0pF	3.0V to 3.6V	2	12	200	
t _{PZH}	G low to Yn active	C _L = 50pF	4.5V to 5.5V	2	11	ns	
	G low to Yn active	C _L = 50pF	3.0V to 3.6V	1	11	ns	
t _{PZL}	G low to Yn active	CL – SUPF	4.5V to 5.5V	1	10	ns	
	G high to Vo these state	C - F0pF	3.0V to 3.6V	2	11	200	
t _{PHZ}	G high to Yn three-state	C _L = 50pF	4.5V to 5.5V	2	14	ns	
	Chish to Yeath as a state	C - 50×5	3.0V to 3.6V	2	8		
t _{PLZ}	G high to Yn three-state		\overline{G} high to Yn three-state $C_L = 50pF$	4.5V to 5.5V	2	9	ns

Notes:

- 1. Maximum allowable relative shift equals 50mV.
- 2. Device type 02 is only offered with a TID tolerance guarantee of 3E5 rads(Si) or 1E6 rads(Si) and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A and section 3.11.2. Device type 03 is only offered with a TID tolerance guarantee of 1E5 rads, 3E5 rads(Si), and 5E5 rads(Si), and is tested in accordance with MILSTD-883 Test Method 1019 Condition A.

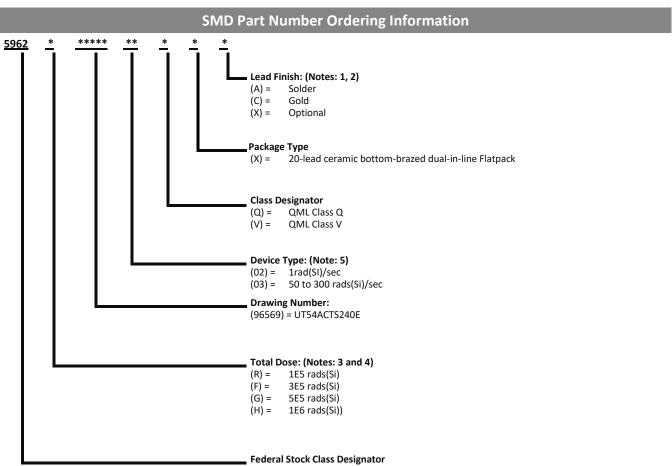


Packaging





Ordering Information



Notes:

- 1. Lead finish (A,C, or X) must be specified.
- 2. If an "X" is specified when ordering, part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
- 3. Total dose radiation must be specified when ordering. QML Q and QML V not available without radiation hardening. For prototype inquiries, contact factory.
- 4. Device type 02 is only offered with a TID tolerance guarantee of 3E5 rads(Si) or 1E6 rads(Si) and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A and section 3.11.2. Device type 03 is only offered with a TID tolerance guarantee of 1E5 rads(Si), 3E5 rads(Si), and 5E5 rads(Si), and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A.



Revision History

Date	Revision #	Author	Change Description	Page #
1-19		RS	Last official release	

Datasheet Definitions

	Definition
Advanced Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is still in the development stage and the datasheet is subject to change . Specifications can be TBD and the part package and pinout are not final .
Preliminary Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is in the characterization stage and prototypes are available.
Datasheet	Product is in production and any changes to the product and services described herein will follow a formal customer notification process for form, fit or function changes.

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